Amendments to the Claims:

This listing of claims will replace all prior versions of claims in the application:

Listing of Claims:

1. (Original) A method comprising:

A. providing a substrate having a first surface and a second surface, the first surface being adapted for mounting an electronic device thereon, the substrate including a grid of electrically conductive vias extending from a region proximate the first surface to a region proximate the second surface, each via being one of a signal via, a ground via and a power via;

B. removing at least one of the vias to form a void between at least one ground via and at least one power via; and

C. connecting each of the at least one ground via proximate the void to one of the at least one power vias proximate the void with a filter device proximate the second surface of the substrate.

2. (Original) The method of claim 1 wherein the vias removed in Step B are ground vias.

3. (Original) The method of claim 1 wherein the filter device comprises a capacitor.

4. (Original) The method of claim 1 wherein the vias in the grid are disposed at a first pitch with respect to each other.

5. (Original) The method of claim 1 wherein the void comprises a loop around at least one via.

6. (Original) A method comprising:

A. providing a substrate having a first surface and a second surface, the first surface being adapted for mounting an electronic device thereon;

B. forming a grid of electrically conductive vias extending from a region proximate the first surface to a region proximate the second surface, each via being one of a signal via, a ground via and a power via;

C. removing at least one of the vias to form a void between at least one ground via and at least one power via; and

D. connecting each of the at least one ground via proximate the void to one of the at least one power vias proximate the void with a filter device proximate the second surface of the substrate.

7. (Original) The method of claim 6 wherein the vias removed in Step C are ground vias.

8. (Original) The method of claim 6 wherein the filter device comprises a capacitor.

9. (Original) The method of claim 6 wherein the vias in the grid are disposed at a first pitch with respect to each other.

10. (Original) The method of claim 6 wherein the void comprises a loop around at least one via.

11. (Currently amended) A method comprising:

A. providing a substrate having a first surface and a second surface, the first surface being adapted for mounting an electronic device thereon;

B. forming a grid including a plurality of electrically conductive vias extending from a region proximate the first surface to a region proximate the second surface, each via being one of a signal via, a ground via and a power via, and a void between at least one ground via and at least one power via, ~~each via being one of a signal via, a ground via and a power via and~~ the void being an area lacking at least one via; and

C. connecting one of the at least one ground vias proximate the void to at least one of the at least one power vias proximate the void with a filter device proximate the second surface of the substrate.

12. (Original) The method of claim 11 wherein the vias removed in Step B are ground vias.

13. (Original) The method of claim 11 wherein the filter device comprises a capacitor.

14. (Original) The method of claim 11 wherein the vias in the grid are disposed at a first pitch with respect to each other.

15. (Original) The method of claim 11 wherein the void comprises a loop around at least one via.

16. (New) The method of claim 1 wherein, in Step C, the filter device is disposed proximate the void when connected between the at least one ground via and the at least one power via.

17. (New) The method of claim 6 wherein, in Step D, the filter device is disposed proximate the void when connected between the at least one ground via and the at least one power via.

18. (New) The method of claim 11 wherein, in Step C, the filter device is disposed proximate the void when connected between the at least one ground via and the at least one power via.